

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information material to the patentability of this application as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Prior U.S. Applications:		
Serial No.	Filing Date	Status
N/A		

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

As a named inventor, I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: Joseph P. Abate, Registration No. 30,328; Jay H. Anderson, Registration No. 38,371; Ira D. Blecker, Registration No. 29,894; Steven Capella, Registration No. 33,086; James J. Cioffi, Registration No. P51,564; Harold H. Huberfeld, Registration No. 26,665; Todd M. C. Li, Registration No. 45,554; Anthony N. Magistrale, Registration No. 35,595; Margaret A. Pepper, Registration No. 45,008; H. Daniel Schnurmann, Registration No. 35,791; Tiffany L. Townsend, Registration No. 43,199; all of INTERNATIONAL BUSINESS MACHINES CORPORATION; John E. Hoel, Registration No. 26,279; Christopher A. Hughes, Registration No. 26,914; Edward A. Pennington, Registration No. 32,588; Joseph C. Redmond, Jr., Registration No. 18,753; all of MORGAN & FINNEGAN, L.L.P.

Send all correspondence to: James J. Cioffi, Intellectual Property Law, IBM Corporation, Dept. 18G, Building 300-482, 2070 Route 52, Hopewell Junction, New York 12533.

Direct Telephone Calls to: James J. Cioffi at 845-894-3363

Inventor: **Tien-Jen Cheng**
Signature: Tien-jen Cheng
Residence: 75 Hickory Lane
Bedford, New York 10506
Citizenship: USA
Post Office Address: Same as residence.

7/9/03
Date

Inventor: **David E. Eichstadt**
Signature: David E Eichstadt
Residence: 35 Sunset Place
North Salem, New York 10560
Citizenship: USA
Post Office Address: Same as residence.

7/3/03
Date

Inventor: **Jonathan H. Griffith**
Signature: _____
Residence: 8 Budd Lane
LaGrangeville, New York 12540
Citizenship: USA
Post Office Address: Same as residence.

Inventor: Tien-Jen Cheng
Signature: Tien-jen Cheng
Residence: 75 Hickory Lane
Bedford, New York 10506
Citizenship: USA
Post Office Address: Same as residence.

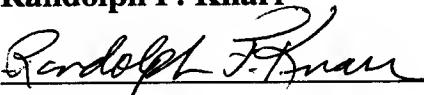
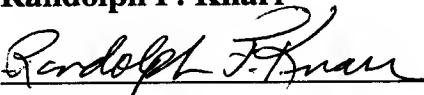
7/9/63
Date

Inventor: David E. Eichstadt
Signature: David E. Eichstadt
Residence: 35 Sunset Place
North Salem, New York 10560
Citizenship: USA
Post Office Address: Same as residence.

7/2/63
Date

Inventor: Jonathan H. Griffith
Signature: Jonathan H. Griffith
Residence: 8 Budd Lane
LaGrangeville, New York 12540
Citizenship: USA
Post Office Address: Same as residence.

7/12/2003
Date

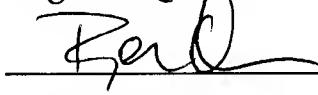
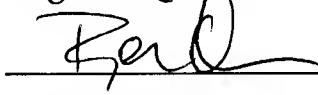
Inventor: **Randolph F. Knarr**

Signature: 
Residence: 26 Quincy Court
Goldens Bridge, New York 10526
Citizenship: USA
Post Office Address: Same as residence.

7/16/03
Date

Inventor: **Kevin S. Petrarca**

Signature: 
Residence: 28 Laurie Lane
Newburgh, New York 12550
Citizenship: USA
Post Office Address: Same as residence.

7/7/03
Date

Inventor: **Roger A. Quon**

Signature: 
Residence: 15 Rockefeller Lane
Rhinebeck, New York 12572
Citizenship: USA CANADA RQ
Post Office Address: Same as residence.

7/21/03
Date

Declaration and Power of Attorney for Patent Application

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name; I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

Encapsulated Pin Structure for Improved Reliability of Wafer

the specification of which (check one)

is attached hereto.

was filed on _____ as Application Serial No. _____ and was amended on _____.

I hereby state that I have reviewed and understand the contents of the above- identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

Number Country

Day/Month/Year

Priority Claimed

N/A